Press release

Hünenberg, 29.10.2026

Quasys Europe takes over European distribution for Grintimate and Longhill

New sales organization expands its portfolio to include solutions for wafer grinding, wafer handling, and other semiconductor manufacturing processes

Quasys Europe is acquiring the European distribution rights for Grintimate and Longhill products. As a result, Quasys Europe will consolidate European distribution of various systems and technologies for the processing, handling, and further processing of wafers. These two partnerships are key components in the development of the new European sales organization. Quasys Europe aims to connect specialized international manufacturers of semiconductor equipment with European semiconductor companies. In addition to providing users with access to innovative technologies, this approach enables the company to offer comprehensive regional consulting and support.

Grintimate: High-precision grinding technology for wafer processing

Grintimate specializes in the development and manufacturing of state-of-the-art hydrostatic grinding machines. A key focus is on systems for high-precision grinding to reduce the thickness of wafers as well as hard and brittle materials, which are increasingly used in demanding semiconductor applications. The product portfolio includes single- and multi-spindle wafer grinders, as well as rotary surface grinders and cylindrical grinders. “Grintimate’s grinders meet the high demands of modern semiconductor processes in terms of precision, surface quality, process stability, and productivity,” explains Rolf Nussbaumer, CEO of Quasys AG.



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Hydrostatic bearing technology forms a central technological foundation. A pressurized liquid film separates the moving components from one another and prevents direct mechanical contact. This reduces wear and vibration while simultaneously ensuring high thermal and mechanical stability. Particularly in the high-precision machining of wafers, this creates important conditions for reproducible processes and consistently high machining quality.

Solutions for Si, SiC, GaN, and other challenging materials

Grintimate’s systems are designed to process a variety of wafer materials. In addition to silicon (Si), these include, in particular, hard and brittle materials such as silicon carbide (SiC), gallium nitride (GaN), sapphire, and ceramics. As a result, the systems are suitable for applications in power electronics and modern compound semiconductor technologies, as well as other fields. In this area in particular, the requirements for wafer thickness, surface quality, and process control are constantly increasing.

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For users, this means that even materials that are difficult to process can be grinded or thinned with high precision and process stability. Depending on the specific system, various automation and process concepts are also available. Multi-spindle systems, for example, allow for the combination of rough and fine grinding processes within a single system design.

Longhill expands portfolio in wafer handling and wafer processing

With Longhill Industries, Quasys Europe is expanding its portfolio to include specialized equipment for key processes in the semiconductor back-end. The product lineup includes systems for back grinding, dicing, die attach film (DAF), as well as wafer handling, sorting, and packaging. A key technology is the patented “Roller-LESS” vacuum process. In this process, wafers and tape or film are brought together inside a vacuum chamber without a conventional pressure roller. This enables gentle, void-free processing with uniform contact pressure and is particularly suitable for thin, warped, pumped, or sensitive wafers.

The portfolio ranges from automatic wafer tapers and detapers to wafer mounters and DAF laminators, as well as systems for wafer ID, UV curing, and wafer transfer, inspection, sorting, and packing. State-of-the-art handling technologies, such as Bernoulli grippers, also support the safe processing of particularly thin and challenging wafers. For users, this results in significant advantages in terms of process reliability, gentle wafer handling, automation, and reproducible processing. Longhill thus complements Grintimate’s grinding technologies and enables Quasys Europe to cover additional related wafer processing steps from a single source.

Focus on automation and process reliability

In particular, the combination of Grintimate’s and Longhill’s product portfolios enables Quasys Europe to meet a wide range of requirements in wafer processing and wafer handling. While Grintimate focuses on high-precision grinding and thinning processes, Longhill’s solutions complement the portfolio, particularly with handling, mounting, taping, lamination, transfer, and identification processes. This provides European users with broader access to specialized semiconductor technologies through a single point of contact. At the same time, automated processes can help reduce manual intervention and lower costs, while supporting reproducible workflows and increasing process reliability in manufacturing.

By acquiring the distribution rights, Quasys Europe will take over the central management of European prospects and customers for both manufacturers. This provides companies with a regional point of contact, from the selection of suitable systems through technical coordination and configuration to support for specific projects. At the same time, Grintimate and Longhill gain direct access to the European semiconductor market through Quasys Europe and can strategically expand their presence in Europe.

“With Grintimate and Longhill, we are gaining two partners whose technologies complement each other very well and align with our strategic direction. Our goal with Quasys Europe is not simply to offer European customers individual machines, but to provide added value throughout the entire manufacturing process. We aim to build a technologically integrated portfolio for various process steps in semiconductor manufacturing, thereby bridging the gap between innovative Asian technology companies and the European market,” explains Nussbaumer. This also includes Quasys Europe establishing a technology center to demonstrate and evaluate its comprehensive solutions for customers on-site.

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About Quasys
Since 1989, Quasys AG has been supplying the Swiss and European markets with production equipment, consumables, and technical solutions for microelectronics, particularly in the areas of feeders, test sockets, bonding tools, and packaging equipment.

At its Hünenberg location, the company combines reliable standard solutions with expert advice and flexible support, innovation, precision, and industry-specific know-how, as well as services that form the basis for efficient automation and bonding solutions in microelectronics.

For more information, visit: http://www.quasys.ch/en/

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